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RECEIPT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor : Michiaki MARUOKA
Serial No : 10/024,103
Filed : DECEMBER 17, 2001
Title : SEMICONDUCTOR DEVICE HAVING BONDING PAD
ELECTRODE OF MULTI-LAYER STRUCTURE

March 29, 2002

Attn: Customer Corrections Division
Assistant Commissioner for Patents
Washington, D.C. 20231

REQUEST FOR CORRECTED FILING RECEIPT

SIR:

We received the filing receipt on the above-referenced case, copy enclosed,
wherein the **FOREIGN APPLICATION** was omitted. Please add:

JAPAN PATENT APPLICATION NO. 2000-394040 FILED DECEMBER 26, 2000.

Any fee, due as a result of this paper may be charged on Deposit Account No. 50-1290.

**ANY FEE DUE WITH THIS PAPER, NOT FULLY
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Respectfully submitted,

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Docket No.: 10080600068(NECB 19.265)
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by Regina Kraussmann

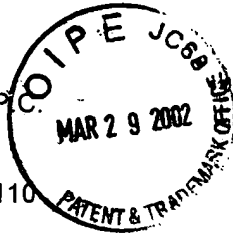


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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/024,103	12/17/2001	2812	740	NECB 19.265	11	20	2

HELFGOTT & KARAS P.C.
60th Floor
Empire State Building
New York, NY 10118-0110



CONFIRMATION NO. 3507

FILING RECEIPT



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Date Mailed: 01/29/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Michiaki Maruoka, Tokyo, JAPAN;

Domestic Priority data as claimed by applicant

Please insert:

Foreign Applications

*Japanese Patent Application No: 2000-394080
Filed: December 26th, 2000*

If Required, Foreign Filing License Granted 01/29/2002

Projected Publication Date: 06/19/2003

Non-Publication Request: No

Early Publication Request: No

Title

Semiconductor device having bonding pad electrode of multi-layer structure

Preliminary Class

438

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